

(0.635 mm) .025"

MEC6-DV SERIES

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(4.22 mm) .166" to

(5.66 mm) .223"

Current Rating:

2.4 A per pin

(2 pins powered)

Voltage Rating:

185 VAC / 262 VDC

RoHS Compliant:

Yes

Mates with:

(1.60 mm) .062" thick card

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.062" thick card

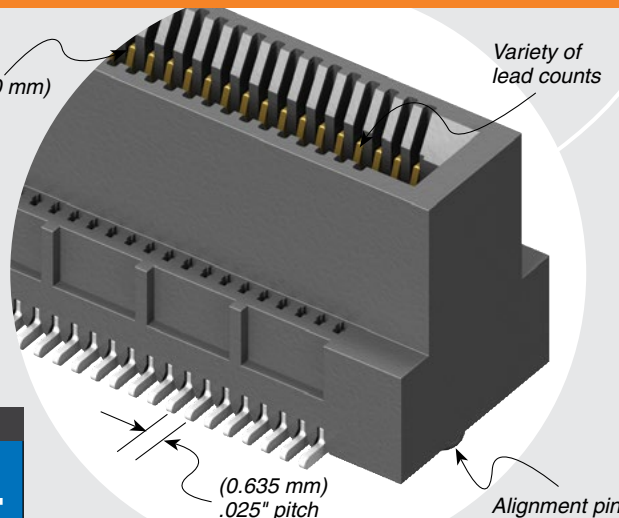
Variety of
lead counts

HIGH-SPEED CHANNEL PERFORMANCE

MEC6-DV

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

14
Gbps



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (10-50)

(0.15 mm) .006" max (60-70)*

*(.004" stencil solution

may be available; contact

IPG@samtec.com)

RECOGNITIONS

For complete scope of
recognitions see

www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Locking Clip
(Manual placement required)
- Other platings

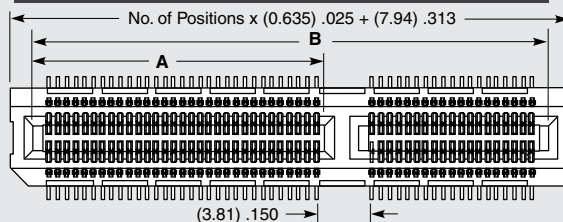
Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some sizes, styles and options are non-standard, non-returnable.



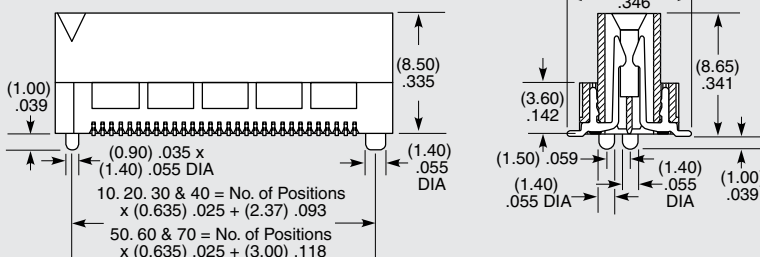
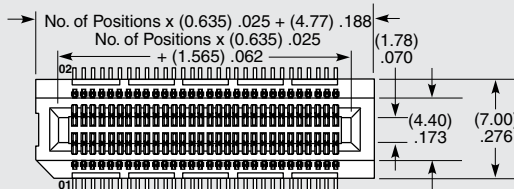
10, 20, 30, 40, 50, 60, 70



—L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail

—K
= (5.50 mm) .217" DIA
Polyimide Pick
& Place Pad

—TR
= Tape & Reel



POSITIONS PER ROW	A	B
50	(21.06) .829	(36.49) 1.437
60	(24.87) .979	(42.84) 1.687
70	(28.68) 1.129	(49.19) 1.937

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.